

May 2024

FAN7390A High-Current, High & Low-Side, Gate-Drive IC

Features

- Floating Channels for Bootstrap Operation to +600 V
- Typically 4.5 A / 4.5 A Sourcing / Sinking Current Driving Capability
- Common-Mode dv/dt Noise-Canceling Circuit
- Built-in Under-Voltage Lockout for Both Channels
- Matched Propagation Delay for Both Channels
- Logic (V_{SS}) and Power (COM) Ground ±5V Offset
- 3.3 V and 5 V Input Logic Compatible
- Output In-phase with Input

Applications

- Plasma Display Panel (PDP) S tain Dri r
- High Intensity Discharr (L...) L on Be List
- SMPS
- Motor Driver

Description

The FAN7390A is a more unic high and low-side gate drive IC, which can already and low-specific and IGBTs that operate to 10 V. If has a buffer of output stage with all IMOS lines, designed for high pulse current during lines and minimum cross-conduction.

Fair "'s the ge process and common-mode ise and techniques provide stable operation of the high side driver under high-th/dt noise circumstants. An advanced level-soft circuit offers high-side gate driver contation in to $V_S = -9.8 \text{ h}'$ (typical) for $V_{BS} = 15 \text{ h}'$

The UVLO sircuit prevents halfunction when V_{DD} and V_{BS} are lower than the specified threshold voltage.

The righ-current and low-output voltage-drop feature make this privide suitable for the PDP sustain pulse driver moto, driver, switching power supply, and high-power DC-DC converter applications.



Ordering Information

Part Number	Package	Operating Temperature Range	Packing Method
FAN7390AMX1	14-SOP	-40°C ~ 125°C	Tape & Reel

Æ

Typical Application Circuit

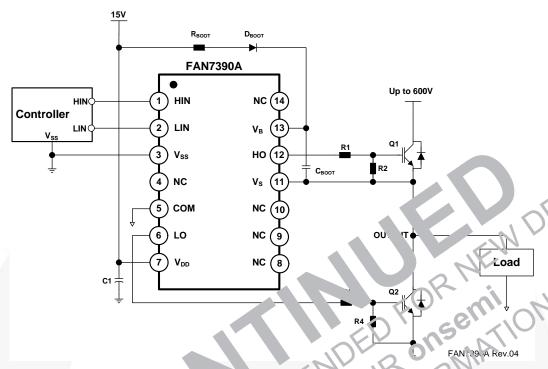


Figure 1. Ar in the Circ or Half-Bridge (Referenced 14 SCF)

Internal Block Dir Jram

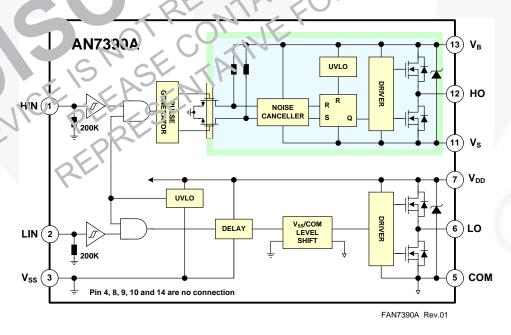


Figure 2. Functional Block Diagram (Referenced 14-SOP)

Pin Configurations

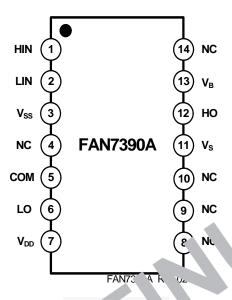


Figure 3. in Ass nmen (Top View)

Pin Definitions

14-Pin	Name	Description
1	HIN	Locic Input for rigin-Side Gate Driver Output
2	LIIV	Logic Input for Low-Side Gate Driver Output
3	V _{SS}	Log c Ground
	COM	Low-Side Driver Return
	LO	Low Side Driver Output
	V_{DL}	Lcw-Side and Logic Part Supply Voltage
21	Vs	High-Voltage Floating Supply Return
12	HO	High-Side Driver Output
13	VB	High-Side Floating Supply
4, 8, 9, 10, 14	NC	No Connect

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only. $T_A=25^{\circ}C$, unless otherwise specified.

Symbol	Characteristics	Min.	Max.	Unit
V _S	High-Side Floating Supply Offset Voltage	V _B -V _{SHUNT}	V _B +0.3	V
V _B	High-Side Floating Supply Voltage	-0.3	625.0	V
V _{HO}	High-Side Floating Output Voltage, HO Pin	V _S -0.3	V _B +0.3	V
V_{DD}	Low-Side and Logic Fixed Supply Voltage	-0.3	V _{SHUNT}	V
V_{LO}	Low-Side Output Voltage, LO Pin	-0.3	V _{DD} +0	V
V _{IN}	Logic Input Voltage (HIN and LIN)	V _{SS} -0.3	// D+r ,	V
V_{SS}	Logic Ground	V _{DD} -25	V _D - `0.3	V
dV _S /dt	Allowable Offset Voltage Slew Rate		50	//r.s
P _D ⁽¹⁾⁽²⁾⁽³⁾	Power Dissipation		U.	A W
$\theta_{\sf JA}$	Thermal Resistance, Junction-to-Ambient		110	°C/W
TJ	Junction Temperature		v i50	°C
T _{STG}	Storage Temperature		+150	E

Notes:

- 1. Mounted on 76.2 x 114.3 x 1.6 mm PCB /FR-4 s ss epc material)
- 2. Refer to the following standards:

JESD51-2: Integral circuits the lance me od environmental conditions - natural convection; and JESD51-3: Low effective then all condulivity test bears for leaded surface mount packages.

3. Do not exceed PD may have uncorany cumstances.

Recomme ded Opc ...ing Conditions

The Recordended Or rating Conditions trade defines the conditions for actual device operation. Recommended on the condition of the specific to ensure optimal performance to the datasheet specifications. Fairchild does not some the reding them or designing to absolute maximum ratings.

Vm ol	Pa; arneter	Min.	Max.	Unit
V _B	եյigh-Տյо∋ Floating Տաբլ ly Voltage	V _S +10	V _S +20	V
V	High-Side Floating Supply Offset Voltage	6-V _{DD}	600	V
V _{HO}	High-Side Cutput Voltage	Vs	V_{B}	V
V_{DD}	Low Side and Logic Supply Voltage	10	20	V
V_{LO}	Low-Side Output Voltage	COM	V_{DD}	V
V _{IN}	Logic Input Voltage (HIN and LIN)	V _{SS}	V _{DD}	V
T _A	Operating Ambient Temperature	-40	+125	°C

Electrical Characteristics

 V_{BIAS} (V_{DD} , V_{BS})=15.0 V, V_{S} = V_{SS} =COM, T_{A} =25°C, unless otherwise specified. The V_{IL} , V_{IH} , and I_{IN} parameters are referenced to V_{SS} /COM and are applicable to the respective input signals HIN and LIN. The V_{O} and I_{O} parameters are referenced to COM and V_{S} is applicable to the respective output signals HO and LO.

Symbol	Characteristics	Condition	Min.	Тур.	Max.	Unit
POWER S	SUPPLY SECTION (V _{DD} AND V _{BS})				•	•
V _{DDUV+} V _{BSUV+}	V _{DD} and V _{BS} Supply Under-Voltage Positive-Going Threshold		8.0	8.8	9.8	
V _{DDUV} - V _{BSUV} -	V _{DD} and V _{BS} Supply Under-Voltage Negative-Going Threshold		7.4	8.3	9.0	V
V _{DDUVH} V _{BSUVH}	V _{DD} and V _{BS} Supply Under-Voltage Lockout Hysteresis Voltage					
I _{LK}	Offset Supply Leakage Current	V _B =V _S =600 V			50	G
I _{QBS}	Quiescent V _{BS} Supply Current	V _{IN} =0 V or 5 V		4F	80	μA
I_{QDD}	Quiescent V _{DD} Supply Current	V _{IN} =0 V or 5 V		/5	110	
I _{PBS}	Operating V _{BS} Supply Current	f _{IN} =20 kHz, rms ue		530	640	μA
I _{PDD}	Operating V _{DD} Supply Current	f _{IN} =20 kHz, r. va	-	530	640	μΛ
SHUNT	REGULATOR SECTION		2			
V _{SHUNT}	V _{DD} and V _{BS} Shunt Regulator Clamping Voltage	Sweep,	21	25	25	V
LOGIC IN	PUT SECTION (HIN, LIN)		Va	77	7	
V _{IH}	Logic "1" Input Voltage	1000	2.5	1		V
V_{IL}	Logic "0" Input Voltage	TE TO THE	127		1.2	v
I _{IN+}	Logic "1" Input Bias C rent	V _{1N} =5 V		25	50	μA
I _{IN-}	Logic "0" Input Pin Cu ent	V _{IN} =0 V		1.0	2.0	μΛ
R _{IN}	Input Pull-do n Resistan	VO 25	100	200		ΚΩ
GATE DR	IVER CTPL SECT N (HO. 20)	(1,50,				
V _{OH}	Hig -Leve' Outp stage, VBIA3-VO	No Load			1.0	V
V _{OL}	nw-Level C tput Voltage, Vo	No Load			35	mV
0+	Onur. an, Short-Circuit Prised Current (4)	$V_O=0$ V, $V_{IN}=5$ V,PW<10 μ s	3.5	4.5		Α
10-	Dut, at Low, Short-Crouit Passed Current(")	V_{O} =15 V, V_{IN} =0 V,PW<10 µs	3.5	4.5		
	Allowable Negative V _S Pin Voltage for HIN Signal Propagation to HO			-9.8	-7.0	V
V _{SS} - C()M	V _{SS} -COM/COM-V _{SS} Voltage Endurability		-5		5	V

Nota:

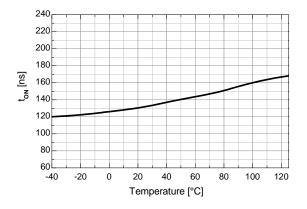
4. This parameter guaranteed by design.

Dynamic Electrical Characteristics

 $V_{BIAS} \ (V_{DD}, \ V_{BS}) = 15.0 \ V, \ V_{S} = V_{SS} = COM = 0 \ V, \ C_{L} = 1000 \ pF \ and \ T_{A} = 25 ^{\circ}C \ unless \ otherwise \ specified.$

Symbol	Characteristics	Test Condition	Min.	Тур.	Max.	Unit
t _{on}	Turn-On Propagation Delay	V _S =0 V		140	200	
t _{off}	Turn-Off Propagation Delay	V _S =0 V		140	200	
MT	Delay Matching, HS & LS Turn-On/Off			15	50	ns
t _r	Turn-on Rise Time			25	50	
t _f	Turn-off Fall Time			20	45	

Typical Characteristics



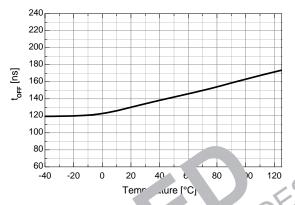
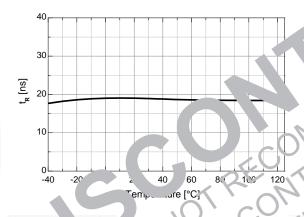


Figure 4. Turn-On Propagation Delay vs. Temperature

Figure 5. rn- Prop jation Delay



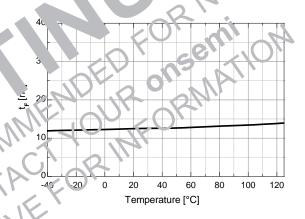
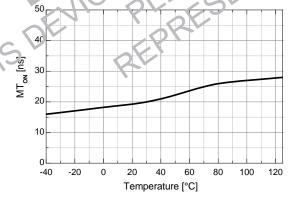


Figure 7. Turn-Off Fall Time

vs. Temperature



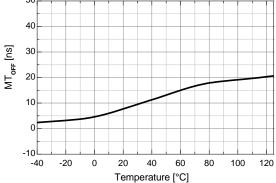
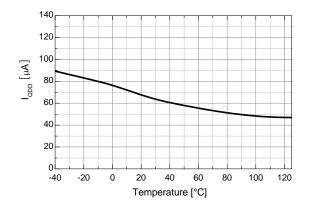


Figure 8. Turn-On Delay Matching vs. Temperature

Figure 9. Turn-Off Delay Matching vs. Temperature

Typical Characteristics (Continued)



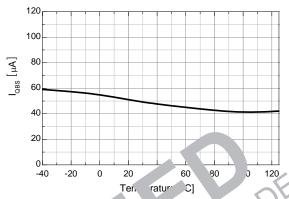
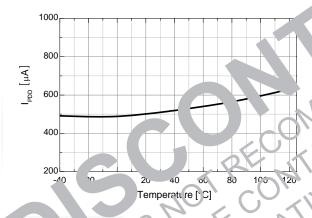


Figure 10. Quiescent V_{DD} Supply Current vs. Temperature

Figure 1. Qui cei as Supply Current vs. emperatule



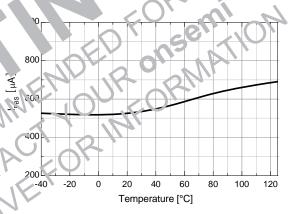
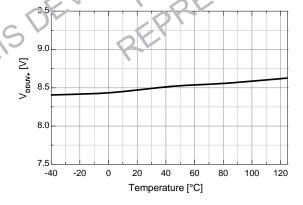


Fig en Operating V_{DD} Supply Current vs. Temperature

Figure 13. Operating V_{BS} Supply Current vs. Temperature



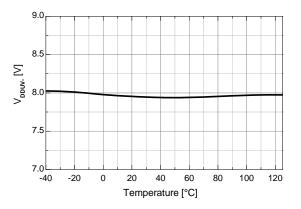
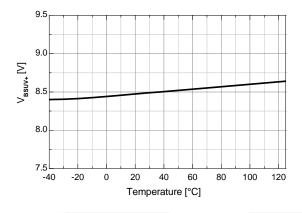


Figure 14. V_{DD} UVLO+ vs. Temperature

Figure 15. V_{DD} UVLO- vs. Temperature

Typical Characteristics (Continued)



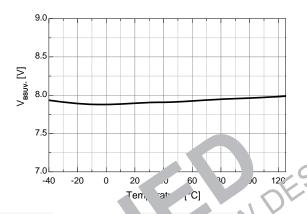
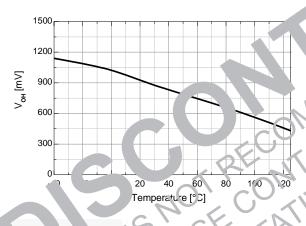
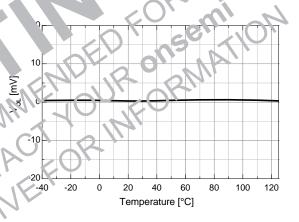


Figure 16. V_{BS} UVLO+ vs. Temperature

Figu. 17. V_b UV.

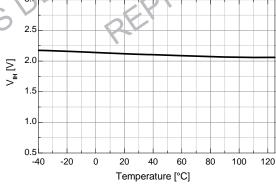




ure 18. High Level Output /oltage ເຮ. Temp⊕rature

Figure 19. Low-Level Output Voltage vs. Temperature

vs. Temperature



vs. Temperature

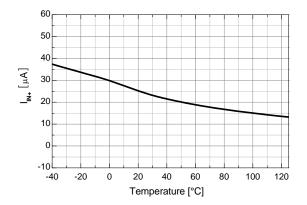
1.0 -40 -20 0 40 Temperature [°C] Figure 20. Logic HIGH Input Voltage Figure 21. Logic LOW Input Voltage

3.0

2.0

100

Typical Characteristics (Continued)



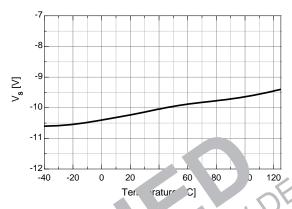


Figure 22. Logic Input High Bias Current vs. Temperature

Figure 3. Allo ablo gative V₃ Voltage vs. emperature

Switching Time Definitions

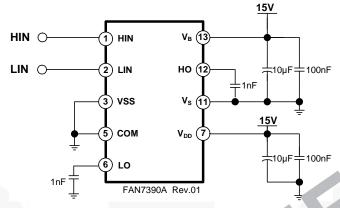


Figure 24. Switching Time Test Circuit (Reference 8-5



____e inp... Outpu\ Timing Dicgram

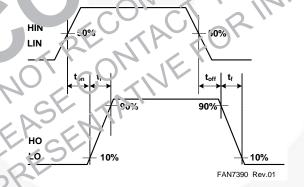


Figure 26. Switching Time Waveform Definitions

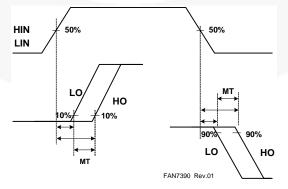
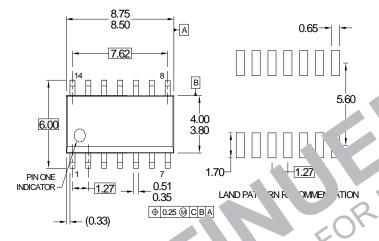


Figure 27. Delay Matching Waveform Definitions

Package Dimensions



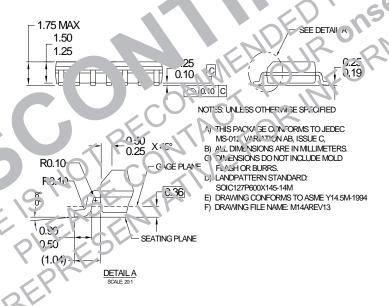


Figure 28. 14-Lead, Small Outline Package (SOP)

Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.

Always visit Fairchild Semiconductor's online packaging area for the most recent package drawings: http://www.fairchildsemi.com/packaging/.



TRADEMARKS

The following includes registered and unregistered trademarks and service marks, owned by Fairchild Semiconductor and/or its global subsidiaries, and is not intended to be an exhaustive list of all such trademarks.

F-PEST 2Cool[†] FRFET® AccuPower™ Global Power ResourceSM AX-CAP™* BitSiC™ GreenBridge™

Green FPS™ Build it Now™ Green FPS™ e-Series™ CorePLUS™

Gmax™ CorePOWFR™ GTO™ CROSSVOLT™ IntelliMAX™ CTI™ ISOPI ANAR™ Current Transfer Logic™

DEUXPEED® Making Small Speakers Sound Louder

and Better Dual Cool™ EcoSPARK® MegaBuck™ MICROCOUPLER™ EfficientMax™ MicroFET** **ESBC™** MicroPak™

MicroPak2™ Fairchild® Miller Drive™ Fairchild Semiconductor® MotionMax™ FACT Quiet Series™ mWSaver™ FACT[®] FAST[®] OptoHiT™ OPTOLOGIC® FastvCore™ OPTOPLANAR®

FETBench¹¹ FlashWriter®* **FPS™**

PowerTrench® PowerXS™

Programmable Active Droop™

OFET® QSIM Quiet Series™ RapidConfigure™

Saving our world, 1mW/W/kW at a time™

SignalWise™ SmartMax™ SMART START™

Solutions for Your Success™

SPM® STEALTH™ SuperFET® SuperSOT™-3 SuperSOT™-6 SuperSOT SupreMOS[®] Sync nc-L

VI DA SYS ENF

The Power Franchise®

p wer TinyBoost™

TinyBuck™ TinyCalc™ TinyLogic® TINYOPTO** TinyPower™ ~WM™

TranSi. TriFault :tect™ 'UF' RRENT Jes™

dnys

L'HC Uhra FRFET UniFET™ VCX™ Visua. Max™ 'vc'ta gePlus™

* Trademarks of System General Corporation, used under licens v Fairch. Semiconductor

ES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE FAIRCHILD SEMICONDUCTOR RESERVES THE TO, KEL. RELIABILITY, FUNCTION, OR DESIGN. FAIRC LO DOL. 101. SSUME ANY LISBILITY ARISING OUT OF THE APPLIE TION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DESIT CL. VEY LY LICENSE; UNDER ITS PAITE TO RIGHTS LYOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE SOF FAIL HILDS WORLD WIDE TERMS AND CONDITION CAFECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODU

LIFE SUPPORT POLICY

EXPRESS WRITTE' APPROVALICE ALLD SEMICENDUCTOR CORPORATION.

As used herei

1. Life support evices or systems are devices or systems which, (a) are rgic jant into the ody or (b) support or sustain hose failure to purform which properly used in i fo. Irgi. accorda wit. Instructions for use provided in the labeling, can be asonal expected to result in a significant injury of the tiser.

A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

ANTI-C .TERFET.NG POLICY

Fairchild Seminal du to Corporation's Anil-Count (feiting Policy, Fairchild's Anti-Counterfeiting Policy is also stated on our external website, www.fairchildsemi.com, under Sales 9 port.

Counter feiting or semiconductor parts is c gr wing problem in the industry. All manufacturers of semiconductor products are experiencing counterfeiting of their prints. Customers who inadvertently rurchs se counterfeit parts experience many problems such as loss of brand reputation, substandard performance, failed applic tions, and increased cost or production and manufacturing delays. Fairchild is taking strong measures to protect ourselves and our customers from the o oliferation of counterfeit parts. Fairchild strongly encourages customers to purchase Fairchild parts either directly from Fairchild or from Authorized Fairchild Distributors who are listed by country on our web page cited above. Products customers buy either from Fairchild directly or from Authorized Fairchild Distributors are genuine parts, have full traceability, meet Fairchild's quality standards for handling and storage and provide access to Fairchild's full range of up-to-date technical and product information. Fairchild and our Authorized Distributors will stand behind all warranties and will appropriately address any warranty issues that may arise. Fairchild will not provide any warranty coverage or other assistance for parts bought from Unauthorized Sources. Fairchild is committed to combat this global problem and encourage our customers to do their part in stopping this practice by buying direct or from authorized distributors.

PRODUCT STATUS DEFINITIONS

Datasheet Identification	Product Status	Definition
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.

Rev. 162



ON Semiconductor and the are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor and severally, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify an

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com

USA/Canada
Europe, Middle East and Africa Technical Support:
Phone: 421 33 790 2910
Japan Customer Focus Center
Phone: 81–3–5817–1050

N. American Technical Support: 800-282-9855 Toll Free

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative